

PC Card, Smart Card and Integrated 1394a-2000 OHCI Two-Port PHY/Link-Layer Controller

FEATURES

- *PC Card Standard 8.0* compliant
- *PCI Bus Power Management Interface Specification 1.1* compliant
- *Advanced Configuration and Power Interface (ACPI) Specification 2.0* compliant
- *PCI Local Bus Specification Revision 2.3* compliant
- PC 98/99 and PC2001 compliant
- Compliant with the *PCI Bus Interface Specification for PCI-to-CardBus Bridges*
- Fully compliant with provisions of IEEE Std 1394-1995 for a high-performance serial bus and IEEE Std 1394a-2000
- Fully compliant with *1394 Open Host Controller Interface Specification 1.1*
- 1.8-V core logic and 3.3-V I/O cells with internal voltage regulator to generate 1.8-V core V_{CC}
- Universal PCI interfaces compatible with 3.3-V and 5-V PCI signaling environments
- Supports PC Card or CardBus with hot insertion and removal
- Supports 132-MBps burst transfers to maximize data throughput on both the PCI bus and the CardBus
- Supports serialized IRQ with PCI interrupts
- Programmable multifunction terminals
- Many interrupt modes supported
- Serial ROM interface for loading subsystem ID and subsystem vendor ID
- ExCA-compatible registers are mapped in memory or I/O space
- Intel 82365SL–DF register compatible
- Supports ring indicate, $\overline{SUSPEND}$, and PCI $\overline{CCLKRUN}$ protocol and PCI bus Lock (\overline{LOCK})
- Provides VGA/palette memory and I/O, and subtractive decoding options, LED activity terminals
- Fully interoperable with FireWire™ and i.LINK™ implementations of IEEE Std 1394
- Compliant with *Intel Mobile Power Guideline 2000*
- Full IEEE Std 1394a-2000 support includes: connection debounce, arbitrated short reset, multispeed concatenation, arbitration acceleration, fly-by concatenation, and port disable/suspend/resume
- Power-down features to conserve energy in battery-powered applications include: automatic device power down during suspend, PCI power management for link-layer, and inactive ports powered down, ultralow-power sleep mode
- Two IEEE Std 1394a-2000 fully compliant cable ports at 100M bits/s, 200M bits/s, and 400M bits/s
- Cable ports monitor line conditions for active connection to remote node
- Cable power presence monitoring
- Separate cable bias (TPBIAS) for each port
- Physical write posting of up to three outstanding transactions
- PCI burst transfers and deep FIFOs to tolerate large host latency
- External cycle timer control for customized synchronization
- Extended resume signaling for compatibility with legacy DV components
- PHY-Link logic performs system initialization and arbitration functions
- PHY-Link encode and decode functions included for data-strobe bit level encoding
- PHY-Link incoming data resynchronized to local clock
- Low-cost 24.576-MHz crystal provides transmit and receive data at 100M bits/s, 200M bits/s, and 400M bits/s
- Node power class information signaling for system power management



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FireWire is a trademark of Apple Computer, Inc..

i.LINK is a trademark of Sony Corporation of America.

- Register bits give software control of contender bit, power class bits, link active control bit, and IEEE Std 1394a-2000 features
- Isochronous receive dual-buffer mode
- Out-of-order pipelining for asynchronous transmit requests
- Register access fail interrupt when the PHY SCLK is not active
- PCI power-management D0, D1, D2, and D3 power states
- Initial bandwidth available and initial channels available registers
- $\overline{\text{PME}}$ support per *1394 Open Host Controller Interface Specification*
- Advanced submicron, low-power CMOS technology

DESCRIPTION

The Texas Instruments PCI7510 device is an integrated single-socket PC Card controller with an IEEE 1394 open host controller link-layer controller (LLC) and two-port 1394 PHY. The PCI7510 device also includes a dedicated interface that can be used as a Smart Card socket. This high performance integrated solution provides the latest in PC Card, IEEE 1394, and Smart Card technology.

The PCI7510 CardBus controller is a four-function, 33-MHz PCI device compliant with the *PCI Local Bus Specification*. Function 0 provides a PC Card socket controller compliant with the latest *PC Card Standards*. Function 1 provides a dedicated socket for Smart Card. Function 2 of the PCI7510 device is an integrated IEEE 1394 OHCI host controller and two-port PHY. Function 3 is the interface to load the PCI7510 program RAM with firmware. The PCI7510 device provides features that make it the best choice for bridging between the PCI bus and PC Cards, and supports any combination of 16-bit and CardBus cards powered at 5 V or 3.3 V as required.

There is no PCMCIA card and socket service software changes required to move systems from the existing CardBus socket controller to the PCI7510 device. The PCI7510 device is register compatible with the Intel 82365SL–DF ExCA controller and implements the host interface defined in the *PC Card Standard*. The PCI7510 internal data path logic allows the host to access 8-, 16-, and 32-bit cards using full 32-bit PCI cycles for maximum performance. Independent buffering and the pipeline architecture provide an unsurpassed performance level with sustained bursting. The PCI7510 device can be programmed to accept posted writes to improve bus utilization. All card signals are internally buffered to allow hot insertion and removal without external buffering.

Function 1 of the PCI7510 device provides a dedicated interface for a Smart Card socket. The PCI7510 device supports asynchronous Smart Cards with contacts.

Function 2 of the PCI7510 device is an integrated 1394a-2000 OHCI PHY/link-layer controller (LLC) device that is fully compliant with the *PCI Local Bus Specification*, the *PCI Bus Power Management Interface Specification*, IEEE Std 1394-1995, IEEE Std 1394a-2000, and the *1394 Open Host Controller Interface Specification*. It is capable of transferring data between the 33-MHz PCI bus and the 1394 bus at 100M bits/s, 200M bits/s, and 400M bits/s. The PCI7510 device provides two 1394 ports that have separate cable bias (TPBIAS). The PCI7510 device also supports the IEEE Std 1394a-2000 power-down features for battery-operated applications and arbitration enhancements.

As required by the *1394 Open Host Controller Interface Specification (OHCI)* and IEEE Std 1394a-2000, internal control registers are memory-mapped and non-prefetchable. The PCI configuration header is accessed through configuration cycles specified by PCI, and it provides plug-and-play (PnP) compatibility. Furthermore, the PCI7510 device is compliant with the *PCI Bus Power Management Interface Specification* as specified by the *PC 2001 Design Guide* requirements. The PCI7510 device supports the D0, D1, D2, and D3 power states.

Function 3 of the PCI7510 device is the interface to load the PCI7510 program RAM with firmware. This function provides an I/O window that a software driver uses to load the PCI7510 firmware into the internal RAM.

The PCI7510 design provides PCI bus master bursting, and it is capable of transferring a cacheline of data at 132M bytes/s after connection to the memory controller. Because PCI latency can be large, deep FIFOs are provided to buffer the 1394 data.

The PCI7510 device provides physical write posting buffers and a highly-tuned physical data path for SBP-2 performance. The PCI7510 device also provides multiple isochronous contexts, multiple cacheline burst transfers, advanced internal arbitration, and bus-holding buffers.

The PCI7510 PHY-layer provides the digital and analog transceiver functions needed to implement a two-port node in a cable-based 1394 network. Each cable port incorporates two differential line transceivers. The transceivers include circuitry to monitor the line conditions as needed for determining connection status, for initialization and arbitration, and for packet reception and transmission.

The PCI7510 PHY-layer requires only an external 24.576-MHz crystal as a reference for the cable ports. An external clock may be provided instead of a crystal. An internal oscillator drives an internal phase-locked loop (PLL), which generates the required 393.216-MHz reference signal. This reference signal is internally divided to provide the clock signals that control transmission of the outbound encoded strobe and data information. A 49.152-MHz clock signal is supplied to the integrated LLC for synchronization and is used for resynchronization of the received data. Data bits to be transmitted through the cable ports are received from the integrated LLC and are latched internally in synchronization with the 49.152-MHz system clock. These bits are combined serially, encoded, and transmitted at 98.304M, 196.608M, or 393.216M bits/s (referred to as S100, S200, or S400 speeds, respectively) as the outbound data-strobe information stream. During transmission, the encoded data information is transmitted differentially on the twisted-pair B (TPB) cable pair(s), and the encoded strobe information is transmitted differentially on the twisted-pair A (TPA) cable pair(s).

Various implementation specific functions and general-purpose inputs and outputs are provided through several multifunction terminals. These terminals present a system with options, such as PCI $\overline{\text{LOCK}}$ and parallel IRQs. ACPI-complaint general-purpose events may be programmed and controlled through the multifunction terminals, and an ACPI-compliant programming interface is included for the general-purpose inputs and outputs.

The PCI7510 device is compliant with the latest *PCI Bus Power Management Specification*, and provides several low-power modes, which enable the host power system to further reduce power consumption. The PCI7510 device also has a four-pin interface compatible with both the TI TPS2211 and TPS2221 power switches.

An advanced CMOS process achieves low power consumption and allows the PCI7510 device to operate at PCI clock rates up to 33 MHz.

NOTE:

This product is for high-volume PC applications only. For a complete datasheet or more information contact support@ti.com.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
PCI7510GHK	OBSOLETE	BGA MI CROSTAR	GHK	209		TBD	SNPB	Level-3-220C-168 HR
PCI7510PDV	ACTIVE	LQFP	PDV	208		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

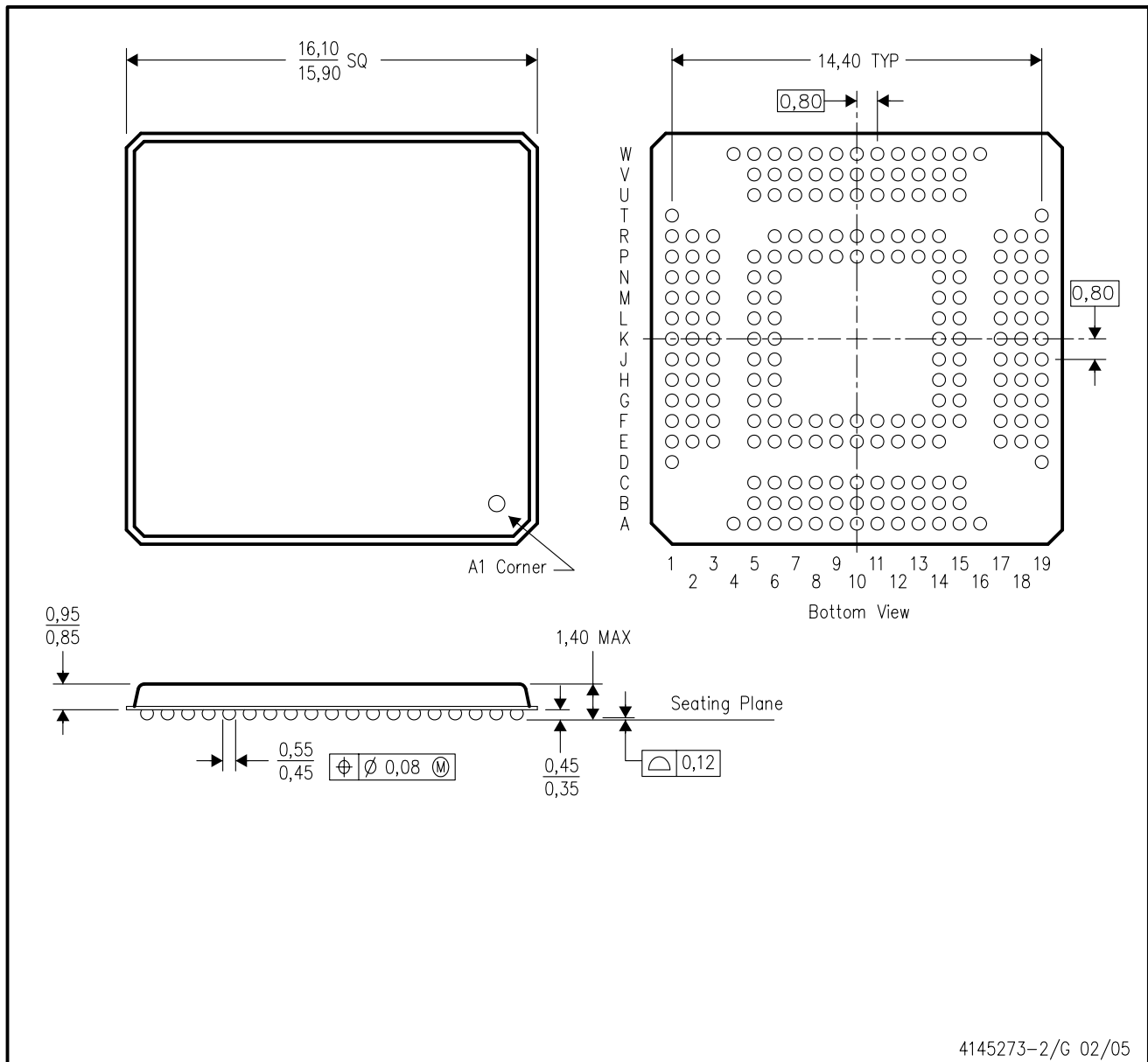
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

GHK (S-PBGA-N209)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated